



Attorney Docket No. 9180-10CT

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Glenn A. Rinne et al;
Application No.: 10/790,967
Filed: March 2, 2004
For: LOW TEMPERATURE METHODS OF BONDING COMPONENTS AND
RELATED STRUCTURES

Group Art Unit: 1725
Examiner: Michael Aboagye

Date: February 1, 2006

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. §1.97(c)

Sir:

Attached is a list of documents on Form PTO-1449, together with a copy of any listed foreign patent document and/or non-patent literature. A copy of any listed U.S. patent and/or U.S. patent application publication is not provided herewith in accordance with the amendment by the U.S. Patent and Trademark Office to 37 C.F.R. § 1.98(a)(2)(ii) effective October 21, 2004.

This Information Disclosure Statement is submitted in accordance with 37 C.F.R. § 1.97(c), before final Office Action or Allowance, whichever is earlier.

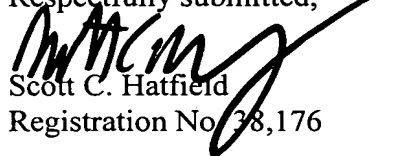
In accordance with the requirements of 37 C.F.R. § 1.97(c)(1), the following Certification as specified in 37 C.F.R. § 1.97(e) is made:

In accordance with the requirements of 37 C.F.R. § 1.97(c)(2), the Commissioner is authorized to charge the \$180.00 fee specified in 37 C.F.R. § 1.17(p) and any deficiency or credit any overpayment to Deposit Account No. 50-0220.

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Application No.: 10/790,967
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It is requested that these documents be considered by the Examiner and
officially made of record in accordance with the provisions of 37 C.F.R. §1.56 and
Section 609 of the MPEP.

Respectfully submitted,

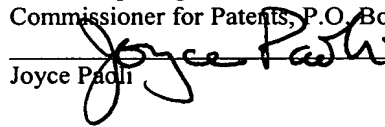


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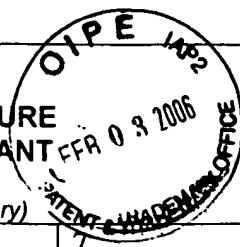
(use as many sheets as necessary)

Sheet

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of

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**Complete if Known**

Application Number	10/790,967
Filing Date	March 2, 2004
First Named Inventor	Glenn A. Rinne
Group Art Unit	1725
Examiner Name	Michael Aboagye
Attorney Docket Number	9180-10CT

U.S. PATENTS AND PATENT PUBLICATIONS

Examiner Initials*	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Number	Kind Code (if known)		
	1.	US-2001/0011764		Elenius et al.	08/2001
	2.	US-2001/0020745		Jiang et al.	09/2001
	3.	US-2001/0042918		Yanagida	11/22/2001
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Examiner Signature

Date Considered

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Substitute form 1449/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)				Complete if Known	
				Application Number	10/790,967
				Filing Date	March 2, 2004
				First Named Inventor	Glenn A. Rinne
				Group Art Unit	1725
Examiner Name	Michael Aboagye				
Sheet	2	of	7	Attorney Docket Number	9180-10CT

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Examiner Signature		Date Considered	
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Substitute form 1449A/PTO				Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Application Number	10/790,967
				Filing Date	March 2, 2004
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				Group Art Unit	1725
				Examiner Name	Michael Aboagye
(use as many sheets as necessary)				Attorney Docket Number	9180-10CT
Sheet	3	of	7		

	102.	US-5,251,806	Agarwala et al.	10/12/1993
	103.	US-5,289,925	Newmark	03/1994
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Examiner Signature		Date Considered	
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				Group Art Unit	1725
				Examiner Name	Michael Aboagye
Sheet	4	of	7	Attorney Docket Number	9180-10CT

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	156.	US-6,117,299		Rinne et al.	09/12/00
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Examiner Initials*	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	T	
		Office	Number	Kind Code (if known)				
	195.	CN	1269607		English Abstract	01/03/2002		
	196.	DE	42 05 029 C		Germany	02/1993	Abstract	
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Examiner Signature		Date Considered	
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				Group Art Unit	1725
				Examiner Name	Michael Aboagye
Sheet	5	of	7	Attorney Docket Number	9180-10CT

	201.	EP	1 148 548		Advanced Interconnect Technology, Ltd.	10-24-2001	
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	225.	JP	54050269			04-1979	Abstract
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	227.	JP	2000349111		Fujitsu, Ltd.	12-15-2000	Abstract
	228.	JP	2002203868		Toshiba Corp	07-19-2002	Abstract
	229.	WO	02/03461		Intel Corporation	01/10/2002	
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	234.	WO	97/03465			01/1997	Abstract
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OTHER NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T
	236.	Adema et al., <i>Flip Chip Technology: A Method for Providing Known Good Die with High Density Interconnections</i> , MCM '94 Proceedings, pp. 41-49.	
	237.	Arai et al. "Sn-Ag Solder Bump Formation for Flip-Chip Bonding by Electroplating" <i>Journal of the Electrochemical Society</i> 150(10): c730-c734 (2003)	
	238.	Audet, et al; <i>Low Cost Bumping Process for Flip Chip</i> , Proc. 1995 International Flip Chip, BGA, and Ado Pkg. Symposium ITAP 95, '95 Flip Chip, BGA, TAB & AP Symposium, pp 16-21 (1995).	
	239.	Chan "Investigation of Cr/Cu/Cu/Ni Under Bump Metallization for Lead-free Applications" <i>2002 Electronics Packaging Technology Conference</i> 270-275 (2002)	
	240.	Choi et al; <i>Electromigration of Flip Chip Solder Bump on Cu/Ni(V) A1 Thin Film Under Bump Metallization</i> ; 2002 Electronic Components and Technology Conference; pp 1201-1205.	
	241.	Datta, et al., <i>Electrochemical Fabrication of Mechanically Robust PbSn C4 Interconnections</i> , J. Electrochem. Soc., vol 142, No. 11, pp 3779-3785 (Nov. 1995).	
Examiner Signature		Date Considered	

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			First Named Inventor	Glenn A. Rinne	
			Group Art Unit	1725	
			Examiner Name	Michael Aboagye	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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